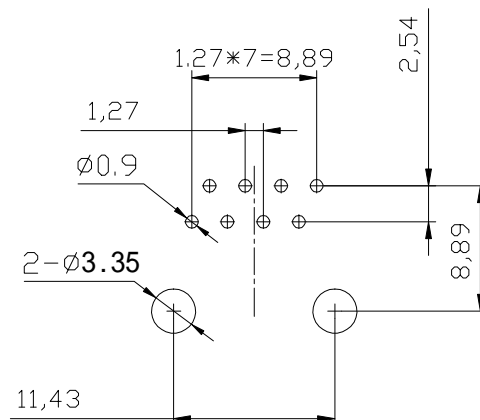
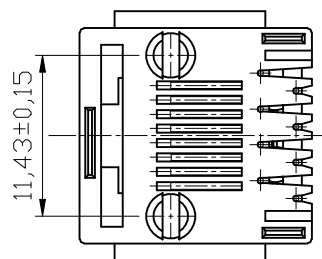
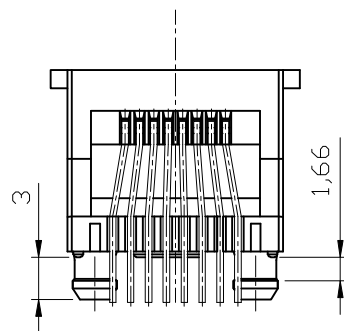
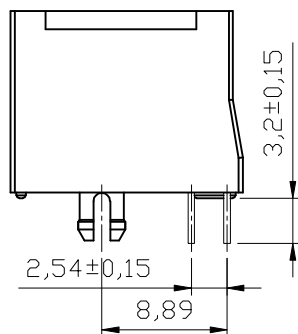
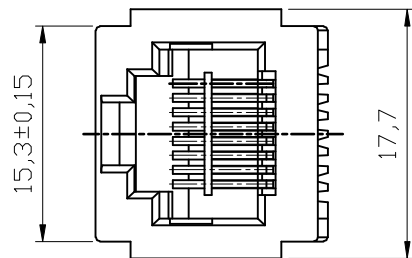


REVISION RECORD				
REV	ECD	DESCRIPTION	DRFT	CHKD



PC Board Layout
Component Side Shown

NOTES:

MATERIAL:

- 1. HOUSING MATERIAL :GLASS FILLED POLYESTER UL94V-0.
- 2. CONTACT MATERIAL :PHOSPHOR BRONZE □=0.46mm.
- 3. PLATING : GOLD PLATING 3u~50u OVER NICKEL

ELECTRICAL:

- 1. VOLTAGE RATING :125 VAC RMS.
- 2. CURRENT RATING :1.5 AMP.
- 3. CONTACT RESISTANCE :30 MILLIOHMS MAX.
- 4. INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC .
- 5. DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

- 1. DURRABILITY: :750 CYCLES MIN.
- 2. PCB RETENTION PRE-SOLDER :1 LB MIN.

ENVIRONMENTAL:

- 1. STORAGE : -40° C TO 85° C.
- 2. OPERATION : 0° C TO 70° C.

PART NUMBER:

ZP52A 8 X - X X X X X X							
52A SERIES JACK							
POSITIONS	CONTACTS	PEG	PANEL	PLASTIC	COLOR	LOGO	GOLD PLATING
4-4 POSITIONS	2-2 CONTACTS	1-SPLIT LONG PEG	0-W/D PANEL	1-PBT	1-BLACK	0-W/D LOGO	1-15u"
6-6 POSITIONS	4-4 CONTACTS	2-SPLIT SHORT PEG	1-W/ PANEL	2-NYLON66	2-WHITE	1-W/ ZPY	2-3u"
8-8 POSITIONS	6-6 CONTACTS	3-"L" PEG		3-NYLON46	3-GRAY	2-W/ UL	3-6u"
1-10 POSITIONS	8-8 CONTACTS			4-ABS	4-IVORY	3-W/ ZPY&UL	4-15u"
	1-10 CONTACTS						5-30u"
							6-50u"

DETACHED LISTS	MM (INCH)	DFTO: SHB	DATE: 2007.05.05	连兴旺电子(深圳)有限公司 LXWCONN ELECTRONICS(SHENZHEN)CO.,LTD
	TOLERANCES EXCEPT AS NOTED	CHKD: LANBO	DATE: 2007.05.05	
	MM	MFO:	DATE:	
	.0 ± 0.15 ±	APPVL:	DATE:	
.00 ± 0.075 ±	MATERIAL :	TITLE		52 TOP ENYRY JACK 8P8C DRAWING NO. TE52A1001 /PART NO. 52A-8P8C-E-13H
.000 ± 0.05 ±	ANGLES ± 0.5	QT'Y :	DRAWING NO. TE52A1001	
THIRD ANGLE PROJECTION	FINISH :	SCALE :	/PART NO. 52A-8P8C-E-13H	
DD NOT SCALE DRAWING			SHEET	OF